

TMOS Power MOSFETs Products

In Brief . . .

Motorola continues to build a world class portfolio of TMOS Power MOSFETs with new advances in silicon and packaging technology. The following new advances have been made in the area of silicon technology.

- New high voltage devices with voltages up to 1200 volts.
- New High Cell Density (HDTMOS) family of standard and Logic Level devices in both N and P-channel are available in DPAK, D²PAK, TO-220 and SO-8 surface mount packages and in the industry standard TO-220 package.
- New TMOS V fifth generation of Motorola Power MOSFET technology. This is a new processing technique that more than doubles the present cell density of our MOSFET devices.
- New Micro8 package is the smallest power MOSFET surface mount package.
- New EZFET™ surface mount power MOSFETs incorporate back to back zener diodes across the gate-to-source to enhance ESD protection.
- New IGBTs with high short circuit capability in TO-220, TO-247 and TO-264 packages.

The following new advances have been made in the area of packaging technology.

- New SO-8 (MiniMOS) and SOT-223 packages to the surface mount portfolio.
- New High Power packages capable of housing very large die and higher power dissipation are now available in the TO-264 (formerly TO-3PBL) and SOT-227B (Isotop) packages.
- New D³PAK package allows the highest power dissipation of any standard, plastic surface-mount power semiconductor.

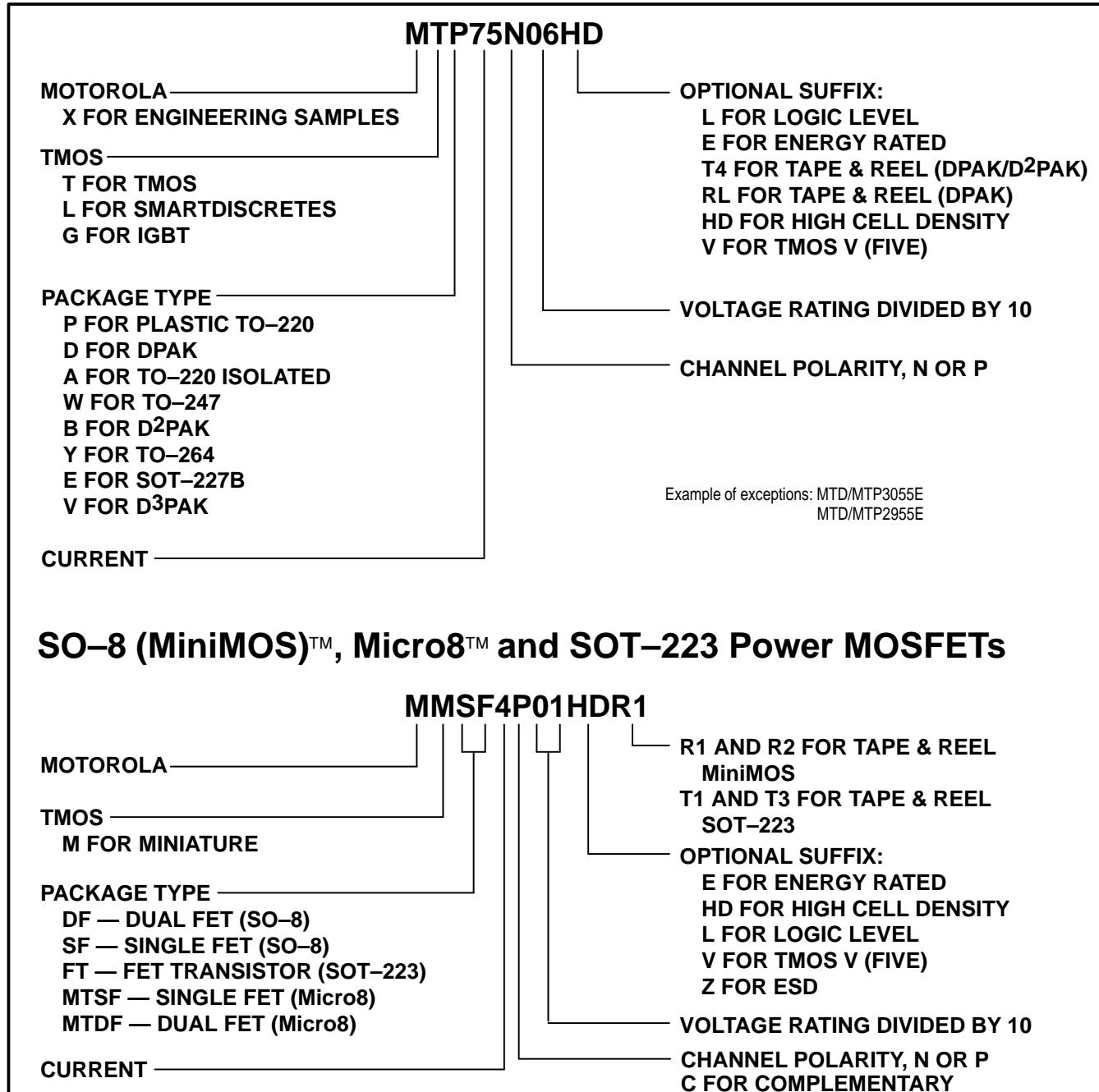
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TMOS Power MOSFETs

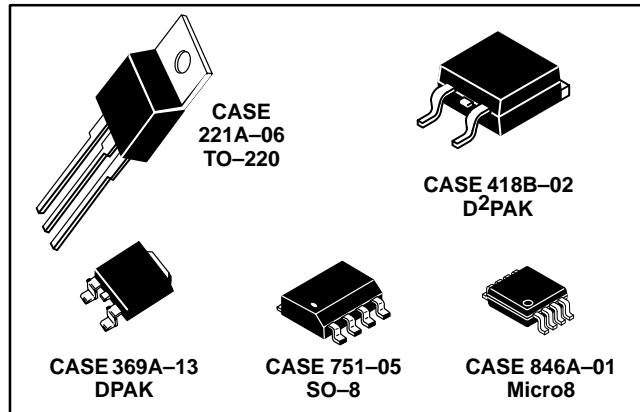
TMOS Power MOSFETs Numbering System

Wherever possible, Motorola has used the following numbering systems for TMOS power MOSFET products.





HDTMOS Power MOSFETs N and P-Channel



HDTMOS Technology is a design technique that reduces the on-resistance contribution in virtually every portion of the power FET. The aggressive six million cells per square inch design is easily manufactured using wafer fabrication techniques that Motorola has used for several years to manufacture highly successful 8-bit microcontrollers.

HDTMOS devices are designed for use in low voltage, high speed switching applications where power efficiency is important. Typical applications are dc-dc converters and power management in portable and battery powered products such as computers, printers, cellular and cordless phones. They can also be used for low voltage motor controls in mass storage products such as disk drives and tape drives.

Table 1. High Power

V(BR)DSS (V)	R _{DS(on)} @ V _{GS}			ID (A)	Motorola Part Number	Package Type
	10 V (mΩ)	5 V (mΩ)	2.7 V (mΩ)			
60	45	—	—	20	<i>MTD20N06HD</i> ⁽⁴⁾	DPAK
	—	45	—	20	<i>MTD20N06HDL</i> ⁽⁴⁾	DPAK
	—	150	—	15	<i>MTD20P06HDL</i> ⁽⁴⁾⁽⁵⁾	DPAK
	10	—	—	75	<i>MTB75N06HD</i> ⁽⁴⁾	D ² PAK
	14	—	—	60	<i>MTB60N06HD</i> ⁽⁴⁾	D ² PAK
	10	—	—	75	<i>MTP75N06HD</i>	TO-220
	14	—	—	60	<i>MTP60N06HD</i>	TO-220
50	9.50	—	—	75	<i>MTP75N05HD</i>	TO-220
	9.50	—	—	75	<i>MTB75N05HD</i> ⁽⁴⁾	D ² PAK
30	—	35	—	20	<i>MTD20N03HDL</i> ⁽⁴⁾	DPAK
	—	99	—	19	<i>MTD20P03HDL</i> ⁽⁴⁾⁽⁵⁾	DPAK
	6.0	7.5	—	75	<i>MTB75N03HDL</i> ⁽⁴⁾	D ² PAK
	—	30	—	50	<i>MTB50P03HDL</i> ⁽⁴⁾⁽⁵⁾	D ² PAK
	6.0	7.5	—	75	<i>MTP75N03HDL</i>	TO-220
	—	30	—	50	<i>MTP50P03HDL</i> ⁽⁵⁾	TO-220

(4) Available in tape and reel — add T4 suffix to part number.

(5) Indicates P-Channel

Devices listed in bold, italic are Motorola preferred devices.

HDTMOS Power MOSFETs (continued)

Table 2. SOIC — COMPLEMENTARY, N and P-Channel

V(BR)DSS (V)	RDS(on) @ VGS			ID (A)	Device ⁽⁵⁾	Package Type	PD ⁽³⁾ (Watts) Max
	10 V (mΩ)	4.5 V (mΩ)	2.7 V (mΩ)				
50	300	500	—	1.5	MMDF1N05E	SO-8	1.5
30	200	300	—	2	MMDF2P03HD	SO-8	1.5
	100	110	—	3	MMSF3P03HD	SO-8	1.5
	70/200(11)	75/300(11)	—	2	MMDF2C03HD	SO-8	1.5
	70	75	—	2.8	MMDF3N03HD	SO-8	1.5
	40	50	—	5	MMSF5N03HD	SO-8	1.5
20	250	400	—	2	MMSF2P02E	SO-8	1.5
	250	400	—	2	MMDF2P02E	SO-8	1.5
	160	180	—	2	MMDF2P02HD	SO-8	1.5
	100/250(11)	200/400(11)	—	2	MMDF2C02E	SO-8	1.5
	100	200	—	2	MMDF2N02E	SO-8	1.5
	90/160(11)	100/180(11)	—	2	MMDF2C02HD	SO-8	1.5
	90	100	—	3	MMDF3N02HD	SO-8	1.5
	75	95	—	3	MMSF3P02HD	SO-8	1.5
	25	40	—	5	MMSF5N02HD	SO-8	1.5
12	—	180	220	2	MMDF2P01HD	SO-8	1.5
	—	100	110	4	MMSF4P01HD	SO-8	1.5
	—	45/180(11)	55/220(11)	2	MMDF2C01HD	SO-8	1.5
	—	45	55	4	MMDF4N01HD	SO-8	1.5

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(5) Available in tape and reel only — R1 suffix = 500/reel, R2 suffix = 2500/reel.

(11) N-Channel/P-Channel RDS(on)

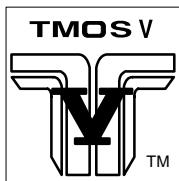
Table 3. EZFET

V(BR)DSS (Volts) Min	Device	Description	RDS(on) (mΩ) Max	VGS (Volts)	ID (cont) Amps	VGS (Volts) Max	Package		
20	MMSF3P02Z	Single P-Channel	75	10	3	±15	SO-8		
			90	4.5					
	MMSF4P01Z		70	4.5	4	±8			
			90	2.7					
30	MMSF6N01Z	Single N-Channel	25	4.5	6				
	MMDF4N01Z	Dual N-Channel	30	2.7					
			45	4.5	4				
	MMSF5N03Z	Single P-Channel	55	2.7					
			30	10	5	±15			
			40	4.5					

Table 4. Micro8

V(BR)DSS (Volts) Min	RDS(on) (mΩ) Max	VGS (Volts)	ID (cont) Amps	Device	Product Description
20	190	2.7	2	MTSF1P02HD	Single P-Channel
20	200	2.7	1.5	MTDF1N02HD	Dual N-Channel
30	75	4.5	3	MTSF3N03HD	Single N-Channel
30	225	4.5	1.5	MTDF1N03HD	Dual N-Channel

Devices listed in bold, italic are Motorola preferred devices.



TMOS V

Motorola Introduces Fifth Generation TMOS Technology

Power Products Division introduces a new technology in the low voltage TMOS transistor family. This new generation technology is currently referred to as TMOS V. It is revolutionary rather than evolutionary.

The TMOS V technology will more than double the present cell density of our TMOS Power MOSFETs. This new technology will result in a tighter overall distribution of electrical parameters and optimizes the performance of our 50 and 60 volt portfolio.

This is a high cell density process of the future that will produce a new line of industry standard devices. Power transistors can now be built with the same high resolution/small geometry MOS fabrication technology that is standard in Motorola's ASIC, microprocessor and Memory Wafer Fabs.

Table 1. TMOS V — DPAK N-Channel

$V_{(BR)DSS}$ (Volts) Min	RDS(on) (Ohms) Max	@	I_D (Amps)	Device	I_D (cont) Amps	P_D (Watts) Max
60	0.150		6	<i>MTD3055V</i> (4)	12	1.75(3)
	0.180		6	<i>MTD3055VL</i> (2)(4)	12	1.75(3)
	0.120		7.5	<i>MTD15N06V</i> (4)	15	1.75(3)
	0.120		7.5	<i>MTD15N06VL</i> (2)(4)	15	1.75(3)
	0.100		10	<i>MTD20N06V</i> (4)	20	1.75(3)

Table 2. TMOS V — TO-220AB N-Channel

$V_{(BR)DSS}$ (Volts) Min	RDS(on) (Ohms) Max	@	I_D (Amps)	Device	I_D (cont) Amps	P_D (Watts) Max
60	0.150		6	<i>MTP3055V</i>	12	48(1)
	0.180		6	<i>MTP3055VL</i> (2)	12	48(1)
	0.120		7.5	<i>MTP15N06V</i>	15	55(1)
	0.120		7.5	<i>MTP15N06VL</i> (2)	15	65(1)
	0.100		10	<i>MTP20N06V</i>	20	65(1)
	0.040		16	<i>MTP36N06V</i>	32	90(1)
	0.050		15	<i>MTP30N06VL</i> (2)	30	90(1)
	0.028		21	<i>MTP50N06V</i>	42	125(1)
	0.032		21	<i>MTP50N06VL</i> (2)	42	125(1)
	0.024		26	<i>MTP52N06V</i>	52	135(1)
	0.028		26	<i>MTP52N06VL</i> (2)	52	135(1)

(1) $T_C = 25^\circ\text{C}$

(2) Indicates logic level

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

Devices listed in bold, italic are Motorola preferred devices.

TMOS V (continued)

Table 3. TMOS V — D²PAK N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device	I_D (cont) Amps	P_D (Watts) Max
60	0.120	7.5	<i>MTB15N06V</i> ⁽⁴⁾	15	3.0(3)
	0.120	7.5	<i>MTB15N06VL</i> ⁽²⁾⁽⁴⁾	15	3.0(3)
	0.100	10	<i>MTB20N06V</i> ⁽⁴⁾	20	3.0(3)
	0.040	16	<i>MTB36N06V</i> ⁽⁴⁾	32	3.0(3)
	0.050	15	<i>MTB30N06VL</i> ⁽²⁾⁽⁴⁾	30	3.0(3)
	0.028	21	<i>MTB50N06V</i> ⁽⁴⁾	42	3.0(3)
	0.032	21	<i>MTB50N06VL</i> ⁽²⁾⁽⁴⁾	42	3.0(3)
	0.024	26	<i>MTB52N06V</i> ⁽⁴⁾	52	3.0(3)
	0.028	26	<i>MTB52N06VL</i> ⁽²⁾⁽⁴⁾	52	3.0(3)

Table 4. TMOS V — SOIC-8

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device	I_D (cont) Amps	P_D (Watts) Max
60	0.150	0.85	<i>MMDF3055V</i> ⁽⁴⁾	1.7	1.8(3)
	0.180	0.75	<i>MMDF3055VL</i> ⁽²⁾⁽⁴⁾	1.5	1.8(3)

Table 5. TMOS V — SOT-223

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device	I_D (cont) Amps	P_D (Watts) Max
60	0.150	0.85	<i>MMFT3055V</i> ⁽⁴⁾	1.7	0.96(3)
	0.180	0.75	<i>MMFT3055VL</i> ⁽²⁾⁽⁴⁾	1.5	0.96(3)

Table 6. TMOS V — P-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device	I_D (cont) Amps	P_D (Watts) Max
60	0.450	2.5	<i>MTD5P06V</i> ⁽⁴⁾	5	1.75(3)
	0.450	2.5	<i>MTP5P06V</i>	5	40(1)
	0.300	6	<i>MTD2955V</i> ⁽⁴⁾	12	1.75(3)
	0.300	6	<i>MTP2955V</i>	12	55(1)
	0.120	11.5	<i>MTB23P06V</i> ⁽⁴⁾	23	3.0(3)
	0.120	11.5	<i>MTP23P06V</i>	23	90(1)
	0.080	15	<i>MTP30P06V</i>	30	125(1)
	0.080	15	<i>MTB30P06V</i> ⁽⁴⁾	30	3.0(3)

(1) $T_C = 25^\circ\text{C}$

(2) Indicates logic level

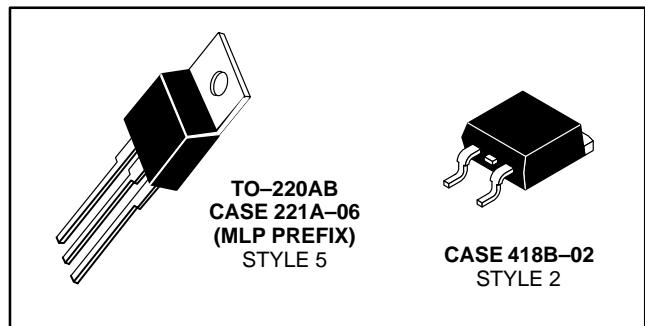
(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

Devices listed in bold, italic are Motorola preferred devices.



SMARTDISCRETES Products



From a standard power MOSFET process, several active and passive elements can be obtained that provide on-chip protection to the basic power device. Such elements require only a small increase in silicon area and/or the addition of one masking layer to the process. The resulting device exhibits significant improvements in ruggedness and reliability and a system cost reduction. These SMARTDISCRETES™ functions can now provide an economical alternative to smart power ICs for power applications requiring low on-resistance, high voltage and high current.

These devices make up a series of "smart" power devices that automatically clamp spikes in automotive ignition systems and guard against ESD. The devices feature a logic level IGBT (Insulated Gate Bipolar Transistor) with integral active collector clamp and ESD gate protection and are designed primarily as ignition coil drivers to withstand high current in a pulsed mode without latching.

Table 1. Ignition IGBTs

BV _{CES} (Volts) Clamped	V _{CE(on)} @ 10 A	Device	P _D ⁽¹⁾ (Watts) Max	Package
140 V	1.8	MGP20N14CL	150	TO-220AB
350 V	1.8	MGP20N35CL MGB20N35CL	150	TO-220AB
400 V	1.8		2.5(3)(4)	D ² PAK
		MGP20N40CL MGB20N40CL	150	TO-220AB
			2.5(3)(4)	D ² PAK

(1) T_C = 25°C

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) DPAK and D²PAK packages available in tape and reel — add T4 suffix to part number.

The MLP1N06CL is a SMARTDISCRETES device that has integrated on-chip current limit capability, drain-to-source voltage clamping and gate voltage protection. The logic level processing allows operation of this device at half of the gate-to-source (5 volts) voltage of the conventional MOSFETs and can now be driven directly from CMOS or TTL logic drivers. This integration of technologies results in an intelligent, monolithic power circuit that offers a reduced parts count and improved reliability by replacing resistors, diodes, a bipolar transistor and a MOSFET with one device all of which are packaged in a TO-220AB package.

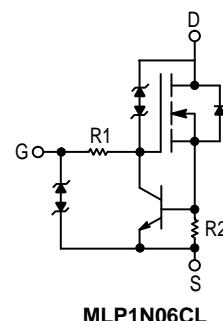


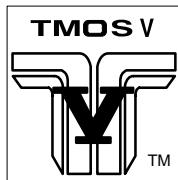
Table 2. TO-220AB — MLP1N06CL

V _{(BR)DSS} (Volts) Min	R _{D(on)} (Ohms) Max	I _D (Amps)	Device	I _D (cont) Amps	P _D ⁽¹⁾ (Watts) Max
60 Clamped Voltage	0.75	1	MLP1N06CL	Current Limited	40
62 Clamped Voltage	0.4	2	MLP2N06CL	Current Limited	40

(1) T_C = 25°C

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

Devices listed in bold, italic are Motorola preferred devices.



CASE 751-05
SO-8
STYLE 11, STYLE 13

CASE 846A-01
Micro8

N-Channel

SO-8 MiniMOS™ and Micro8 Surface Mount Products

MiniMOS devices are an advanced series of power MOSFETs which utilize Motorola's High Cell Density HDTMOS process. These miniature surface mount MOSFETs feature ultra low $R_{DS(on)}$ and true logic level performance.

MiniMOS devices are designed for use in low voltage, high speed switching applications where power efficiency is important. Typical applications are dc-dc converters and power management in portable and battery powered products such as computers, printers, cellular and cordless phones. They can also be used for low voltage motor controls in mass storage products such as disk drives and tape drives.

- Ultra Low $R_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life
- Logic Level Gate Drive — Can Be Driven by Logic ICs
- Miniature SO-8 Surface Mount Package — Saves Board Space
- Diode Is Characterized for Use In Bridge Circuits
- Diode Exhibits High Speed, with Soft Recovery
- I_{DSS} and $V_{DS(on)}$ Specified at Elevated Temperature
- Avalanche Energy Specified

Table 1. SO-8 Products — N-Channel

$V(BR)DSS$	$R_{DS(on)}$ @ V_{GS}			I_D (A)	Device ⁽⁵⁾	Package Type	P_D ⁽³⁾ (Watts) Max
	(V) 10 V (mΩ)	(V) 4.5 V (mΩ)	(V) 2.7 V (mΩ)				
50	300	500	—	1.5	MMDF1N05E	SO-8	1.5
30	40	50	—	5	MMSF5N03HD	SO-8	1.5
	70	75	—	2.8	MMDF3N03HD	SO-8	1.5
	70/200(11)	75/300	—	2	MMDF2C03HD	SO-8	1.5
20	25	40	—	5	MMSF5N02HD	SO-8	1.5
	90	100	—	3	MMDF3N02HD	SO-8	1.5
	100	200	—	2	MMDF2N02E	SO-8	1.5
	90/160(11)	100/180(11)	—	2	MMDF2C02HD	SO-8	1.5
	100/250(11)	200/400(11)	—	2	MMDF2C02E	SO-8	1.5
	12	—	45	55	MMDF4N01HD	SO-8	1.5
	—	45/180(11)	55/220(11)	2	MMDF2C01HD	SO-8	1.5

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(5) Available in tape and reel only — R1 suffix = 500/reel, R2 suffix = 2500/reel.

(11) N-Channel/P-Channel $R_{DS(on)}$

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



N-Channel

SO-8 EZFET™ — Power MOSFETs with Zener Gate Protection

- New Family of Low $R_{DS(on)}$ MOSFETs with monolithic back-to-back zener diodes across the gate to source.
- HDTMOS™ Technology (High Cell Density TMOS)
- Extremely Low $R_{DS(on)}$ provides higher efficiency and increased battery life in portable applications

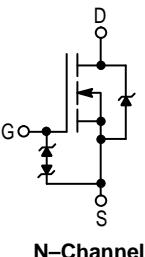


Table 2. EZFET

$V_{(BR)DSS}$ (Volts) Min	Device	Description	$R_{DS(on)}$ (mΩ) Max	@ V_{GS} (Volts)	I_D (cont) Amps	V_{GS} (Volts) Max	Package
20	MMSF6N01Z	Single N-Channel	25 30	4.5 2.7	6	±8	SO-8
	MMDF4N01Z	Dual N-Channel	45 55	4.5 2.7	4		

Table 3. Micro8

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (mΩ) Max	@ V_{GS} (Volts)	I_D (cont) Amps	Device	Product Description
20	200	2.7	1.5	MTDF1N02HD	Dual N-Channel
30	75	4.5	3	MTSF3N03HD	Single N-Channel
30	225	4.5	1.5	MTDF1N03HD	Dual N-Channel

SOT-223 Medium Power MOSFETs Surface Mount Products

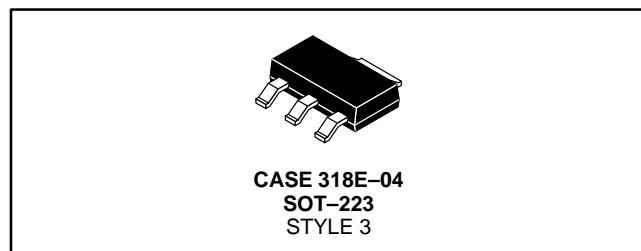


Table 4. SOT-223 Medium Power TMOS FETs — N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) @ Max	I_D (Amps)	Device ⁽¹²⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max	Applications
100	0.30	0.5	MMFT1N10E	1	0.8 ⁽³⁾	dc-dc Converters Power Supplies Motor Controls, Disk Drives
60	0.18	0.75	MMFT3055EL⁽²⁾	1.5		
	0.15	0.85	MMFT3055E	1.7		
20	0.15	1	MMFT2N02EL⁽²⁾	2		

(1) $T_C = 25^\circ C$

(2) Indicates logic level

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(12) Available in tape and reel only — T1 suffix = 1000/reel, T3 suffix = 4000/reel.

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



CASE 369A-13
TO-252
STYLE 2

N-Channel

DPAK Surface Mount Products

Table 5. DPAK — N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device ⁽⁴⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
800	12	0.5	<i>MTD1N80E</i>	1	1.75 ⁽³⁾
600	8	0.5	<i>MTD1N60E</i>	1	
500	5	0.5	<i>MTD1N50E</i>	1	1.75 ⁽³⁾
	3.60	1	<i>MTD2N50E</i>	2	
400	3.50	1	<i>MTD2N40E</i>	2	1.75 ⁽³⁾
250	1.40	1.5	<i>MTD3N25E</i>	3	
	1	2.5	<i>MTD5N25E</i>	5	1.75 ⁽³⁾
200	1.20	2	<i>MTD4N20E</i>	4	
	0.70	3	<i>MTD6N20E</i>	6	1.75 ⁽³⁾
150	0.30	3	MTD6N15	6	
100	0.60	2.5	<i>MTD5N10E</i>	5	1.75 ⁽³⁾
	0.40	3	<i>MTD6N10E</i>	6	
	0.25	4.5	<i>MTD9N10E</i>	9	
	0.22	5	<i>MTD10N10EL</i> ⁽²⁾	10	
60	0.18	6	<i>MTD3055VL</i> ⁽²⁾	12	1.75 ⁽³⁾
	0.15	6	<i>MTD3055V</i>	12	
	0.12	4	<i>MTD8N06E</i>	8	
	0.12	7.5	<i>MTD15N06V</i>	15	
	0.045	10	<i>MTD20N06HD</i>	20	
	0.045	10	<i>MTD20N06HDL</i> ⁽²⁾	20	
50	0.10	5	<i>MTD10N05E</i>	10	1.75 ⁽³⁾
30	0.035	10	<i>MTD20N03HDL</i> ⁽²⁾	20	

(1) $T_C = 25^\circ\text{C}$

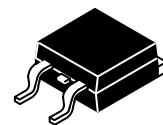
(2) Indicates logic level

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



CASE 418B-02
STYLE 2

N-Channel

D2PAK Surface Mount Products

Table 6. D2PAK — N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	I_D (Amps) @	Device ⁽⁴⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
1200	5	1.5	MTB3N120E	3	2.5 ⁽³⁾
1000	9	0.5	MTB1N100E	1	
	4	1.5	MTB3N100E	3	
800	3	2	MTB4N80E	4	
600	1.20	3	MTB6N60E	6	
500	0.80	4	MTB8N50E	8	
400	0.55	5	MTB10N40E	10	
250	0.50	4.5	MTB9N25E	9	
	0.25	8	MTB16N25E	16	
200	0.16	10	MTB20N20E	20	
100	0.060	16.5	MTB33N10E	33	
60	—	—	MTB15N06V	—	
	0.05	15	MTB30N06EL⁽²⁾	30	
	0.04	16	MTB36N06V	36	
	0.032	21	MTB50N06VL	42	
	0.028	21	MTB50N06V	42	
	0.014	30	MTB60N06HD	60	
	0.01	37.5	MTB75N06HD	75	
50	0.0095	37.5	MTB75N05HD	75	
30	0.0075	37.5	MTB75N03HDL⁽²⁾	75	

(1) $T_C = 25^\circ\text{C}$

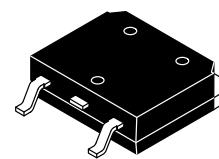
(2) Indicates logic level

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



CASE 433-01
TO-286
STYLE 2

N-Channel

D3PAK

- D3PAK is a high power surface mount package designed to accommodate die which is too large for a D²PAK.
 - Utilized for Size 5, Size 6 or larger MOSFET and IGBT.
 - Used for dual die IGBT and diode combination.
- 24 mm Tape and Reel, 500 units per 13' reel.
- D3PAK is thermal characterized for use on FR-4 and IMS board materials.
- Applications:
 - Surface mount motor drives
 - Power supplies both AC/DC and DC/DC

Table 7. D3PAK — N-Channel

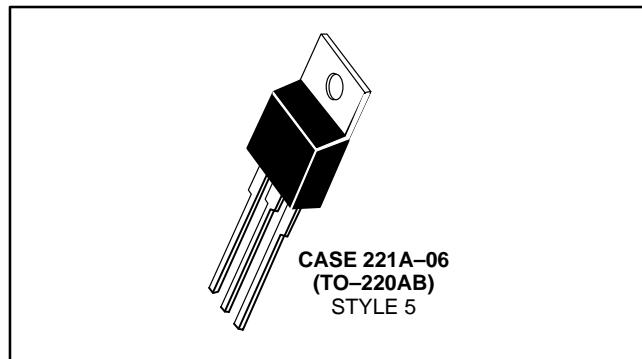
$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device ⁽⁴⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
1000	1.50		3	<i>MTV6N100E</i>	6	178
	1.30		5	<i>MTV10N100E</i>	10	250
500	0.320		8	<i>MTV16N50E</i>	16	250
	0.240		10	<i>MTV20N50E</i>	20	250
	0.200		12.5	<i>MTV25N50E</i>	25	250
250	0.065		16	<i>MTV32N05E</i>	32	250
200	0.075		16	<i>MTV32N20E</i>	32	180

(1) $T_C = 25^\circ\text{C}$

(4) Available in tape and reel — add RL suffix to part number.

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



N-Channel

TO-220AB

Table 8. TO-220AB — N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
1200	5.0		1.5	MTP3N120E	3	125
1000	9		0.5	MTP1N100E	1	75
	4.0		1.5	MTP3N100E	3	125
800	3		2	MTP4N80E	4	
600	8		0.5	MTP1N60E	1	50
	3.80		1	MTP2N60E	2	
	2.20		1.5	MTP3N60E	3	75
	1.20		3	MTP6N60E	6	125
500	5		0.5	MTP1N50E	1	50
	3.60		1	MTP2N50E	2	75
	3		1.5	MTP3N50E	3	50
	1.50		2	MTP4N50E	4	75
	0.80		4	MTP8N50E	8	125
400	3.50		1	MTP2N40E	2	50
	1.80		2	MTP4N40E	4	50
	1		2.5	MTP5N40E	5	75
	0.55		5	MTP10N40E	10	125
250	1.4		1	MTP3N25E	3	40
	0.5		4.5	MTP9N25E	9	75
	0.25		8	MTP16N25E	16	125
200	0.70		3.5	MTP7N20E	7	75
	0.16		10	MTP20N20E	20	125
100	0.25		5	MTP10N10E	10	75
	0.22		5	MTP10N10EL	10	40
	0.16		6	MTP12N10E	12	75
	0.070		13.5	MTP27N10E	27	125
	0.060		16.5	MTP33N10E	33	150

(1) $T_C = 25^\circ\text{C}$

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)

Table 8. TO-220AB — N-Channel (continued)

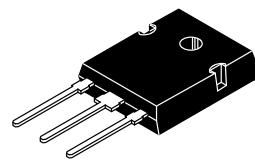
$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
60	0.18	6	<i>MTP3055VL</i> ⁽²⁾	12	48
	0.15	6	<i>MTP3055V</i>	12	
	0.12	7.5	<i>MTP15N06V</i>	15	
	0.12	7.5	<i>MTP15N06VL</i>	15	
	0.10	10	<i>MTP20N06V</i>	20	
	0.05	15	<i>MTP30N06VL</i> ⁽²⁾	30	
	0.04	18	<i>MTP36N06V</i>	32	
	0.032	25	<i>MTP50N06VL</i> ⁽²⁾	50	
	0.028	25	<i>MTP50N06V</i>	50	
	0.028	26	<i>MTP52N06VL</i>	52	
	0.024	26	<i>MTP52N06V</i>	52	
	0.014	30	<i>MTP60N06HD</i>	60	
	0.01	37.5	<i>MTP75N06HD</i>	75	
50	0.10	7.5	<i>MTP15N05EL</i> ⁽²⁾	15	75
	0.0095	37.5	<i>MTP75N05HD</i>	75	
25	0.0075	37.5	<i>MTP75N03HDL</i> ⁽²⁾	75	

(1) $T_C = 25^\circ\text{C}$

(2) Indicates logic level

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



CASE 340F-03
TO-247AE
(MTW PREFIX)
STYLE 1

N-Channel

TO-247 Isolated Mounting Hole

The Motorola portfolio of TO-247 devices has new on-resistance specifications on many industry standard devices with $R_{DS(on)}$ reductions up to 25%.

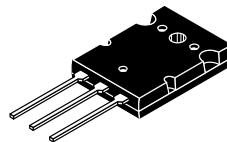
Table 9. TO-247 — N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
1000	1.50		3	MTW6N100E	6	180
	1.30		5	MTW10N100E	10	250
800	1		3.5	MTW7N80E	7	180
600	0.50		4	MTW8N60E	8	180
500	0.32		7	MTW14N50E	14	180
	0.24		10	MTW20N50E	20	250
400	0.24		8	MTW16N40E	16	180
	0.16		12	MTW24N40E	24	250
250	0.10		16	MTW32N25E	32	250
200	0.075		16	MTW32N20E	32	180
150	0.065		17.5	MTW35N15E	35	180
100	0.035		22.5	MTW45N10E	45	180

(1) $T_C = 25^\circ\text{C}$

Devices listed in bold, italic are Motorola preferred devices.

N-Channel (continued)



CASE 340G-02
TO-264

N-Channel

TO-264 High Power Products

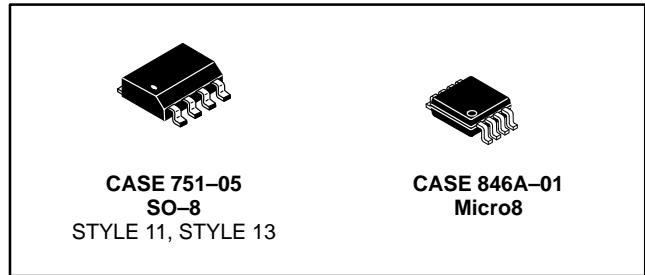
The TO-264 package is a new addition to the Motorola portfolio of high power packages. This package is capable of a power dissipation of 300 Watts and it achieves a low on-resistance with a single die. Lead spacing is compatible to the TO-247 package.

Table 10. TO-264 High Power Products — N-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@ I_D (Amps)	Device	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
600	0.21	12.5	<i>MTY25N60E</i>	25	300
500	0.26	10	<i>MTY20N50E</i>	20	
	0.15	15	<i>MTY30N50E</i>	30	
200	0.028	27.5	<i>MTY55N20E</i>	55	
100	0.011	50	<i>MTY100N10E</i>	100	

(1) $T_C = 25^\circ\text{C}$

Devices listed in bold, italic are Motorola preferred devices.



P-Channel

SO-8 (MiniMOS) and Micro8 Surface Mount Products

Multiple Chip TMOS Products in SOIC Surface Mount Packages

MiniMOS devices are an advanced series of power MOSFETs which utilize Motorola's High Cell Density HDTMOS process. These miniature surface mount MOSFETs feature ultra low R_{DS(on)} and true logic level performance.

MiniMOS devices are designed for use in low voltage, high speed switching applications where power efficiency is important. Typical applications are dc-dc converters and power management in portable and battery powered products such as computers, printers, cellular and cordless phones. They can also be used for low voltage motor controls in mass storage products such as disk drives and tape drives.

Table 1. SO-8 Products — P-Channel

V _{(BR)DSS}	R _{DS(on)} @ V _{GS}			I _D (A)	Device ⁽⁵⁾	Package Type	P _D ⁽³⁾ (Watts) Max
	(V)	10 V (mΩ)	4.5 V (mΩ)				
30	100	110	—	3	MMSF3P03HD	SO-8	1.5
	200	300	—	2	MMDF2P03HD	SO-8	1.5
20	75	95	—	3	MMSF3P02HD	SO-8	1.5
	160	180	—	2	MMDF2P02HD	SO-8	1.5
	250	400	—	2	MMDF2P02E	SO-8	1.5
	250	400	—	2	MMSF2P02E	SO-8	1.5
12	—	100	110	4	MMSF4P01HD	SO-8	1.5
	—	180	220	2	MMDF2P01HD	SO-8	1.5

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(5) Available in tape and reel only — R1 suffix = 500/reel, R2 suffix = 2500/reel.

Table 2. Micro8

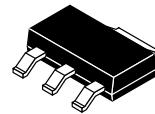
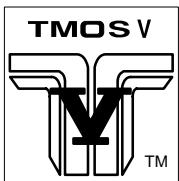
V _{(BR)DSS} (Volts) Min	R _{DS(on)} (mΩ) Max	@ V _{GS} (Volts)	I _D (cont) Amps	Device	Product Description
20	190	2.7	2	MTSF1P02HD	Single P-Channel

Table 3. EZFET

V _{(BR)DSS} (Volts) Min	Device	Description	R _{DS(on)} (mΩ) Max	V _{GS} (Volts)	I _D (cont) Amps	V _{GS} (Volts) Max	Package
20	MMSF3P02Z	Single P-Channel	75	10	3	±15	SO-8
	MMSF4P01Z		90	4.5			
			70	4.5	4	±8	
			90	2.7			

Devices listed in bold, italic are Motorola preferred devices.

P-Channel (continued)



CASE 318E-04
SOT-223
STYLE 3

P-Channel

SOT-223 Medium Power MOSFETs Surface Mount Products

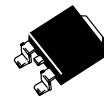
Table 4. SOT-223 Medium Power TMOS FETs — P-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) @ Max	I_D (Amps)	Device(12)	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max	Application
60	0.30	0.6	MMFT2955E	1.2	0.8(3)	dc-dc Converters Power Supplies Motor Controls, Disk Drives

(1) $T_C = 25^\circ\text{C}$

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(12) Available in tape and reel only — T1 suffix = 1000/reel, T3 suffix = 4000/reel.



CASE 369A-13
TO-252
STYLE 2

DPAK Surface Mount Products

Table 5. DPAK — P-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	I_D (Amps)	Device(4)	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
500	15.0	0.5	MTD1P50E	1	1.75(3)
100	0.66	3	MTD6P10E	6	
60	0.55	2.5	MTD5P06E	5	
	—	—	MTD5P06V	—	
	0.15	10	MTD20P06HDL (2)	20	
30	0.099	10	MTD20P03HDL (2)	19	

(1) $T_C = 25^\circ\text{C}$

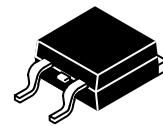
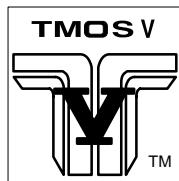
(2) Indicates logic level

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

Devices listed in bold, italic are Motorola preferred devices.

P-Channel (continued)



CASE 418B-02
STYLE 2

P-Channel

D2PAK Surface Mount Products

Table 6. D²PAK — P-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device ⁽⁴⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
500	6		1	<i>MTB2P50E</i>	2	2.5 ⁽³⁾
60	0.12		11.5	<i>MTB23P06E</i>	23	
30	0.025		25	<i>MTB50P03HDL(2)</i>	50	

(1) $T_C = 25^\circ\text{C}$

(2) Indicates logic level

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.



CASE 221A-06
(TO-220AB)
STYLE 5

TO-220AB

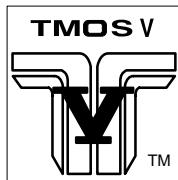
Table 7. TO-220AB — P-Channel

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
500	6		1	<i>MTP2P50E</i>	2	
200	1		3	<i>MTP6P20E</i>	6	
100	0.30		6	<i>MTP12P10</i>	12	88
60	0.45		2.5	<i>MTP5P06V</i>	5	40
	0.30		6	<i>MTP2955V</i>	12	60
	0.12		11.5	<i>MTP23P06V</i>	23	125
	0.08		15	<i>MTD30P06V</i>	30	125
30	0.025		25	<i>MTP50P03HDL(2)</i>	50	150

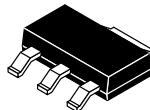
(1) $T_C = 25^\circ\text{C}$

(2) Indicates logic level

Devices listed in bold, italic are Motorola preferred devices.



Logic Level — N-Channel



CASE 318E-04
SOT-223
STYLE 3

SOT-223 Medium Power MOSFETs Surface Mount Products

Table 1. SOT-223 Medium Power TMOS FETs — Logic Level

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) @ Max	I_D (Amps)	Device ⁽¹²⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max	Application
60	0.18	0.75	MMFT3055EL	1.5	0.8 ⁽³⁾	dc-dc Converters Power Supplies Motor Controls, Disk Drives
20	0.15	1		2		

(1) $T_C = 25^\circ C$

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(12) Available in tape and reel only — T1 suffix = 1000/reel, T3 suffix = 4000/reel.

DPAK — N and P-Channel Surface Mount Products



CASE 369A-13
TO-252
STYLE 2

Table 2. DPAK — Logic Level

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) @ Max	I_D (Amps)	Device ⁽⁴⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
100	0.22	5	MTD10N10EL	10	1.75 ⁽³⁾
60	0.12	7.5	MTD15N06V	15	
	0.18	6	MTD3055VL	12	
	0.15	10	MTD20P06HDL ⁽⁵⁾	20	
	0.045	10	MTD20N06HDL	20	
30	0.099	10	MTD20P03HDL ⁽⁵⁾	19	
	0.035	10	MTD20N03HDL	20	

(1) $T_C = 25^\circ C$

(2) Indicates logic level

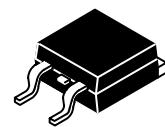
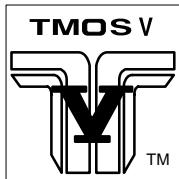
(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

(5) Indicates P-Channel

Devices listed in bold, italic are Motorola preferred devices.

Logic Level (continued)



CASE 418B-02
STYLE 2

Logic Level

D2PAK — N and P-Channel Surface Mount Products

Table 3. D2PAK — Logic Level

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device ⁽⁴⁾	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
60	0.05		15	<i>MTB30N06VL</i>	30	2.5 ⁽³⁾
	0.032		21	<i>MTB50N06VL</i>	42	
30	0.025		25	<i>MTB50P03HDL</i> ⁽⁵⁾	50	
	0.0075		37.5	<i>MTB75N03HDL</i>	75	

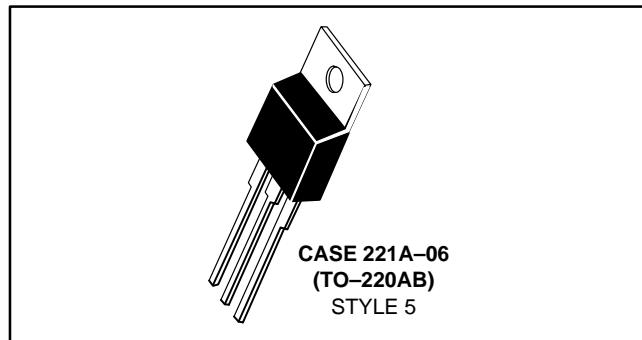
(1) $T_C = 25^\circ\text{C}$

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) Available in tape and reel — add T4 suffix to part number.

(5) Indicates P-Channel

TO-220AB — N and P-Channel



CASE 221A-06
(TO-220AB)
STYLE 5

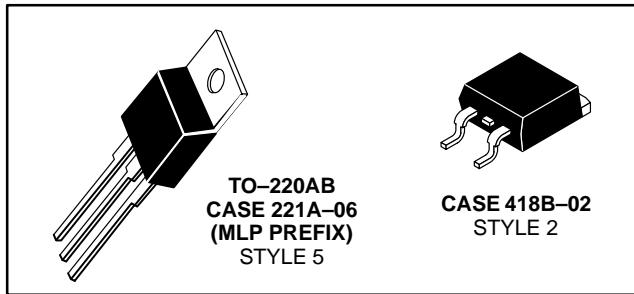
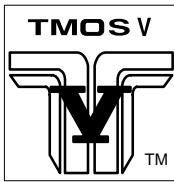
Table 4. TO-220AB — Logic Level

$V_{(BR)DSS}$ (Volts) Min	$R_{DS(on)}$ (Ohms) Max	@	I_D (Amps)	Device	I_D (cont) Amps	$P_D^{(1)}$ (Watts) Max
100	0.22		5	<i>MTP10N10EL</i>	10	75
60	0.18		6	<i>MTP3055EL</i>	12	48
	0.18		6	<i>MTP3055VL</i>	12	
	0.05		15	<i>MTP30N06EL</i>	30	
	0.05		15	<i>MTP30N06VL</i>	30	
	0.028		25	<i>MTP50N06EL</i>	50	
	0.032		21	<i>MTP50N06VL</i>	42	
	0.028		26	<i>MTP52N06VL</i>	50	
50	0.12		7.5	<i>MTP15N06VL</i>	15	65
	0.10		7.5	<i>MTP15N05EL</i>	15	
	0.032		25	<i>MTP50N05EL</i>	50	
30	0.025		25	<i>MTP50P03HDL</i> ⁽²⁾	50	150
	0.0075		37.5	<i>MTP75N03HDL</i>	75	

(1) $T_C = 25^\circ\text{C}$

(2) Indicates P-Channel

Devices listed in bold, italic are Motorola preferred devices.



N-Channel

Insulated Gate Bipolar Transistors (IGBTs)

These devices make up a series of “smart” power devices that automatically clamp spikes in automotive ignition systems and guard against ESD. The devices feature a logic level IGBT (Insulated Gate Bipolar Transistor) with integral active collector clamp and ESD gate protection and are designed primarily as ignition coil drivers to withstand high current in a pulsed mode without latching.

Table 1. N-Channel Ignition IGBTs

BV _{CES} (Volts) Clamped	V _{CE(on)} @ 10 A	Device	P _D ⁽¹⁾ (Watts) Max	Package
140 V	1.8	MGP20N14CL	150	TO-220AB
350 V	1.8	MGP20N35CL	150	TO-220AB
		MGB20N35CL	2.5 ⁽³⁾⁽⁴⁾	D ² PAK
400 V	1.8	MGP20N40CL	150	TO-220AB
		MGB20N40CL	2.5 ⁽³⁾⁽⁴⁾	D ² PAK

(1) T_C = 25°C

(3) Power rating when mounted on an FR-4 glass epoxy printed circuit board with the minimum recommended footprint.

(4) DPAK and D²PAK packages available in tape and reel — add T4 suffix to part number.

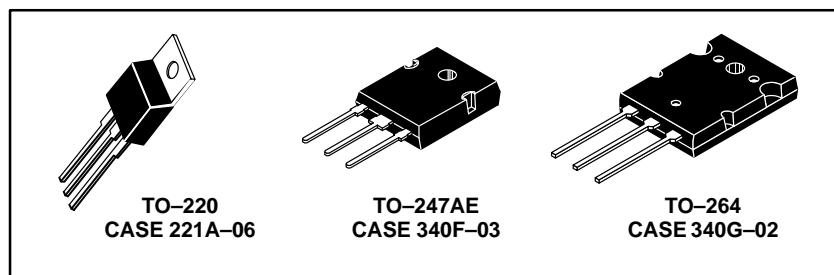


Table 2. N-Channel, Standard and Copackaged IGBTs

Device	BV _{CES} (Volts)	I _C @ 90°C (A)	V _{CE(on)} @ I _C (Volts) Max	P _D ⁽¹⁾ Watts	Package
MGP5N60E	600	5	2.06 V @ 1.5 A	62	TO-220
MGP20N60		20	2.9 V @ 10 A	142	TO-220
MGW20N60D					TO-247
MGW30N60		30	2.9 V @ 15 A	202	TO-247
MGY30N60D					TO-264
MGY40N60		40	2.8 V @ 20 A	260	TO-264
MGY40N60D	1200				TO-264
MGW12N120		12	3.37 V @ 5 A	123	TO-247
MGW12N120D					TO-247
MGY25N120		25	3.24 V @ 12.5 A	212	TO-264

(1) T_C = 25°C

Devices listed in bold, italic are Motorola preferred devices.